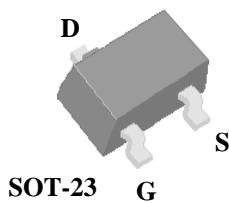
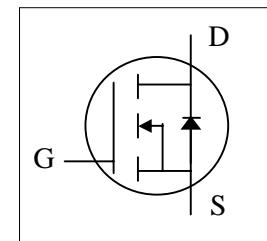


## AP2322GN-HF

- ▼ Capable of 1.8V gate drive
- ▼ Simple Drive Requirement
- ▼ Surface mount package
- ▼ RoHS Compliant & Halogen-Free



$BV_{DSS}$	20V
$R_{DS(ON)}$	90mΩ
$I_D$	2.5A



### Description

Advanced Power MOSFETs utilized advanced processing techniques to achieve the lowest possible on-resistance, extremely efficient and cost-effectiveness device.

The SOT-23 package is widely used for commercial-industrial applications.

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	+8	V
$I_D@T_A=25^\circ C$	Continuous Drain Current <sup>3</sup> , $V_{GS} @ 4.5V$	2.5	A
$I_D@T_A=70^\circ C$	Continuous Drain Current <sup>3</sup> , $V_{GS} @ 4.5V$	2.0	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	10	A
$P_D@T_A=25^\circ C$	Total Power Dissipation	0.833	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	150	°C/W

## AP2322GN-HF

Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	20	-	-	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=1.6\text{A}$	-	-	90	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_D=1\text{A}$	-	-	120	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=1.8\text{V}, \text{I}_D=0.3\text{A}$	-	-	150	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=1\text{mA}$	0.25	-	1	V
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=2\text{A}$	-	2	-	S
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=20\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\text{uA}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage	$\text{V}_{\text{GS}}=+8\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
$\text{Q}_{\text{g}}$	Total Gate Charge <sup>2</sup>	$\text{I}_D=2.2\text{A}$	-	7	11	nC
$\text{Q}_{\text{gs}}$	Gate-Source Charge		-	0.7	-	nC
$\text{Q}_{\text{gd}}$	Gate-Drain ("Miller") Charge		-	2.5	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time <sup>2</sup>	$\text{V}_{\text{DS}}=10\text{V}$	-	6	-	ns
$t_r$	Rise Time		-	12	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	16	-	ns
$t_f$	Fall Time	$\text{V}_{\text{GS}}=5\text{V}$	-	4	-	ns
$C_{\text{iss}}$	Input Capacitance		-	350	560	pF
$C_{\text{oss}}$	Output Capacitance		-	55	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	48	-	pF
$R_g$	Gate Resistance		-	3.2	4.8	$\Omega$

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{V}_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$\text{I}_S=0.7\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1.2	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$\text{I}_S=2\text{A}, \text{V}_{\text{GS}}=0\text{V},$	-	20	-	ns
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge	$d\text{I}/dt=100\text{A}/\mu\text{s}$	-	13	-	nC

## Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board ,  $t \leq 10\text{sec}$  ;  $360^\circ\text{C}/\text{W}$  when mounted on Min. copper pad.